



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

ProCurve 10-GbE CX4 Media Converter (J8439A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm 2 PCBA with surface area of 5 cm and 6 cm respectively	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Slotted Head Screwdriver	2.5 mm
Hex Head Driver	1.5 mm
Hammer	
Punch	
Pliers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove 2 slotted screws from the bottom cover and remove cover.
2. Remove 2 hex screws from the bolster plate between the rigid and the flex PCBs.
3. Lift the rigid PCB out of the housing.
4. Insert punch into the optical port, and hammer the optical assembly loose from the glue holding it in place.
5. The aluminum optical stack may be pried or pulled from the surface of the flex, if desired, prior to disposal.
6. The PCBAs contain small amounts of gold, silver, and solder, which may be reclaimed.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

